PENDING CLAIMS

1-21. (Cancelled)

- (Previously Presented) An apparatus for vaporizing a solid precursor, comprising: an atomic layer deposition (ALD) chamber having a reaction chamber;
- a housing having an inlet for receiving a carrier gas and an outlet in fluid communication with a sealable interior volume, wherein the outlet is operably coupled to the reaction chamber of the atomic layer deposition (ALD) chamber;
- at least two surfaces comprising a mesh material contained in the housing having a solid tantalum-containing precursor applied thereto; and
- a heating member contained within a wall of the housing, wherein at least one of the at least two surfaces is in thermal communication with the wall of the housing.
- (Previously Presented) The apparatus of claim 22, wherein the at least two surfaces are spaced to allow passage of the carrier gas therebetween.
- 24. (Previously Presented) The apparatus of claim 22, wherein the at least two surfaces are formed of a material selected from the group consisting of stainless steel and ceramic.

25-28. (Cancelled)

- (Previously Presented) The apparatus of claim 22, wherein a heating member is contained in one of the at least two surfaces.
- 30. (Previously Presented) The apparatus of claim 22, wherein one of the at least two surfaces is coupled to the housing.
- 31. (Previously Presented) The apparatus of claim 22, wherein the at least two surfaces have a form selected from the group consisting of an s-shape, a linear shape, and a cone shape.

- (Previously Presented) An apparatus for vaporizing a solid precursor, comprising: an atomic layer deposition (ALD) chamber having a reaction chamber;
- a housing having an inlet for receiving a carrier gas and an outlet in fluid communication with a sealable interior volume, wherein the outlet is operably coupled to the reaction chamber of the atomic layer deposition (ALD) chamber:

at least two cone shaped surfaces contained in the housing having a solid tantalum-containing precursor applied thereto: and

a heating member contained within a wall of the housing, wherein at least one of the at least two surfaces is in contact with the wall of the housing.

- (Previously Presented) The apparatus of claim 32, wherein the at least two surfaces are spaced to allow passage of the carrier gas therebetween.
- 34. (Previously Presented) The apparatus of claim 32, wherein the at least two surfaces are formed of a material selected from the group consisting of stainless steel and ceramic
- 35. (Cancelled)
- (Previously Presented) The apparatus of claim 32, wherein a heating member is contained in one of the at least two surfaces.
- 37. (Previously Presented) The apparatus of claim 32, wherein one of the at least two surfaces is coupled to the housing.
- 38. (Cancelled)
- 39. (Previously Presented) The apparatus of claim 22, wherein the at least one of the at least two surfaces is in contact with the wall of the housing.